

NKI Standard/IP Experts

	Activity	Active Years	Highest Position
Rick Adams	Automotive Electronic Council	12	Founding Member
	Semiconductor Assembly Council	10	Chairman of the Board
	JEDEC JC14.1, Reliability Test Methods	20	Sr Member
	JEDEC JC14.3, Silicon Device Qualification Methods	20	Sr Member
	JEDEC/EIAJ US/Japan Joint Reliability Standards Meeting	6	USA Delegate
Mark Bird	JEDEC Board of Directors	10	Vice-Chair
	JEDEC JC-11 Mechanical (Package Outlines) Standardization	30	Chair
	JEDEC JC-11.1 Design Requirements	30	Chair
	JEDEC JC-11.4 Uncased Devices	30	Chair
	JEDEC JC-11.7 IEC Interface	30	Chair
	JEDEC JC-11.11 Microelectronic Plastic Packages	30	Chair
	JEDEC JC-11.14 Microelectronic Assemblies	30	Chair
	JEDEC JC-13 Government Liaison	10	Chair
	JEDEC JC-13.1 Discrete Devices	10	Chair
	JEDEC JC-13.2 Microelectronic Devices	10	Chair
	JEDEC JC-14 Quality and Reliability of Products	15	Vice-Chair
	JEDEC JC-14.1 Reliability Test Methods for Packaged Devices	15	Vice-Chair
	JEDEC JC-14.3 Silicon Devices Reliability Qualification and Monitoring	15	Vice-Chair
	JEDEC JC-14.4 Quality Processes and Methods	15	Vice-Chair
	JEDEC-EIAJ, US/Japan Joint Reliability and Packaging Outline Standards Meeting	20	USA Chair
	IEC TC47, TC47A, TC47D International Semiconductor Standards	15	USA Delegate
	IPC-JEDEC Joint Standards on Moisture, Solderability, and Plating	10	JEDEC Delegate
	Semiconductor Assembly and Packaging Roadmaps for Jisso, ITRS, IPC, and INEMI	10	USA Chapter Chair
	Member of the SMTA Technical Committee and Surface Mount Council	10	Vice Chair

NKI Standard/IP Experts- continued

	Activity	Active Years	Highest Position
Chris Brigham	JEDEC JC-14 Quality and Reliability of Products	20	Sr Member
	JEDEC JC-14.1 Reliability Test Methods for Packaged Devices	20	Vice Chair
	JEDEC JC-14.3 Silicon Devices Reliability Qualification and Monitoring	18	Vice Chair
	JEDEC JC-14.4 Quality Processes and Methods	6	Vice Chair
	JEDEC JC-14.7 Gallium Arsenide Reliability and Quality Standards	3	Sr Member
	JEDEC/EIAJ US/Japan Joint Reliability Standards Meeting	8	Delegate
	JEDEC JC-13 Government Liaison	7	Sr Member
	JEDEC JC-13.1 Discrete Devices	2	Sr Member
	JEDEC JC-13.2 Microelectronic Devices	5	Sr Member
	IPC-JEDEC Joint Standards on Moisture, Solderability, and Plating	8	JEDEC Delegate
	Semiconductor Assembly Council	10	Sr. Member
Matt Doty	JEDEC JC-13.1 Discrete Devices	3	Sr Member
	JEDEC JC-13.2 Microelectronic Devices	3	Sr Member
	JEDEC JC-13.4 Radiation Hardness	3	Sr Member
	JEDEC JC-14 Quality and Reliability of Products	6	Vice Chair
	JEDEC JC-14.1 Reliability Test Methods for Packaged Devices	10	Chair, Vice Chair
	JEDEC JC-14.2 Wafer Level Reliability	3	Sr Member
	JEDEC JC-14.3 Silicon Devices Reliability Qualification and Monitoring	10	Chair, Vice Chair
	IPC-JEDEC Joint Standards on Moisture, Solderability, and Plating	4	JEDEC Delegate
	JEDEC/EIAJ US/Japan Joint Reliability Standards Meeting	6	USA Delegate
	IEC TC47 WG2, International Reliability Standards	4	USA Delegate